

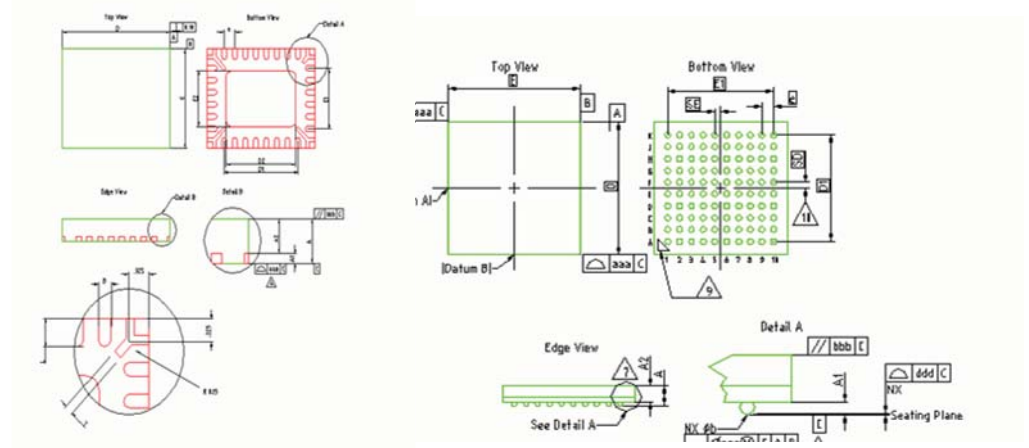
Package Needs Assessment

Involve Unisem Europe at initial design Stage for feasibility review



Package Design

NiPdAu preplated QFN & laminate substrate based BGA & LGA



MEMs Applications

Lidded & premolded cavity packages

